

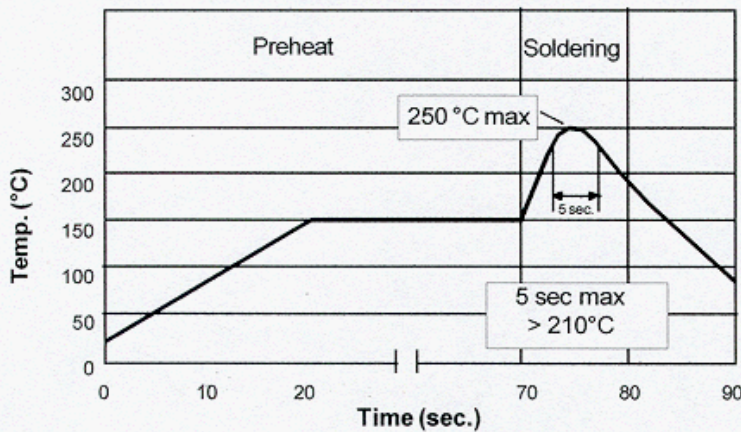


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**FT232BM / FT245BM IR Reflow Profile**

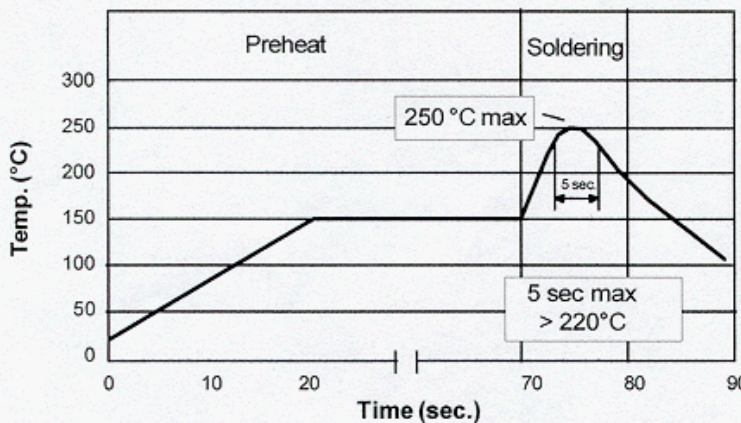
**Wave Soldering**



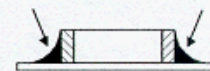
**Soldering Tips**

- Use Sn-Pb crystal type solder with RM or RMA type flux. Acid type flux should be avoided.
- When using a soldering iron:
  - Use 40 W iron or less
  - Apply temp of 250 -270°C for less than 5 sec.
  - Avoid pressing on terminal with iron.
- Solder joints should be smooth with a meniscus as shown in the sketch below.

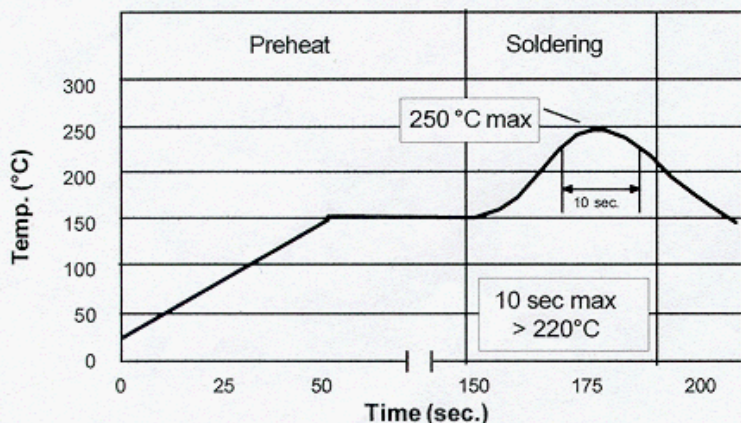
**Flow**



Smooth Solder Joints



**Reflow**



**Cleaning**

- Before cleaning, allow parts to cool slowly. Temperature difference between chip and washing fluid should be less than 100°C.
- Most solvents and wash systems approved for electronic components may be used.
- When using dipping or vapor cleaning methods, liquid temperature should be 70°C. Immersion times should be less than 30 min.
- Ultrasonic cleaning may cause delamination of mica layers. If ultrasonic method must be used, use frequency of 28 KHz @ 70°C for 15 min or less.